

Please amend the application as follows:

**In the Claims:**

Please amend the claims as follows:

25. (amended) The packaged semiconductor device of Claim 24, wherein said layer of nickel has a thickness in the range of about 500 nm to about 3000 nm and said palladium layer has a thickness in the range of about 10 nm to about 30 nm.

26. (amended) The packaged semiconductor device of Claim 24, wherein said gold has a thickness in the range of about 6% to about 50% of said thickness of said palladium layer.

**REMARKS**

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-13, 15 and 23-26 are pending in this application. Claims 25 and 26 have been amended.

Claims 25 and 26 stand rejected under 35 U.S.C. 112, second paragraph. Claims 25 and 26 have been amended to indicate that they depend from Claim 24. As such, the claims are now in statutory form.

Claim 1 stands rejected under 35 U.S.C. 102(e) as being anticipated by Lee, et al. (U.S. Patent No. 6,232,651). Applicant respectfully traverses the rejection. Claim 1 includes the feature of "gold selectively plated on segments of